

### Performance Specification

Model	Vmax (V dc)	Imax (A)	I hold @25C (A)	I trip @25C (A)	Pd Typ. (W)	Max time to Trip		Resistance	
						Current (A)	Time (Sec)	R i min (Ohm)	R i max (Ohm)
0805Z010-15	15.0	100	0.10	0.30	0.5	0.5	1.50	1.000	6.000
0805Z020-09	9.0	100	0.20	0.50	0.5	8.0	0.02	0.650	3.500
0805Z035-06	6.0	100	0.35	0.75	0.5	8.0	0.10	0.250	1.200
0805Z050-06	6.0	100	0.50	1.00	0.5	8.0	0.10	0.150	0.850
0805Z075-06	6.0	40	0.75	1.50	0.6	8.0	0.20	0.090	0.385
0805Z100-06	6.0	100	1.00	1.95	0.6	8.0	0.30	0.060	0.230
0805Z110-06	6.0	100	1.10	2.20	0.6	8.0	0.30	0.060	0.210
0805Z125-06	6.0	100	1.25	2.50	1.5	8.0	0.60	0.030	0.140

I hold = Hold Current. Maximum current device will not trip in 25°C still air.

I trip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V max = Maximum operating voltage device can withstand without damage at rated current (Imax).

I max = Maximum fault current device can withstand without damage at rated voltage (V max).

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Ri min/max = Minimum/Maximum device resistance prior to tripping at 25°C.

R1max = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

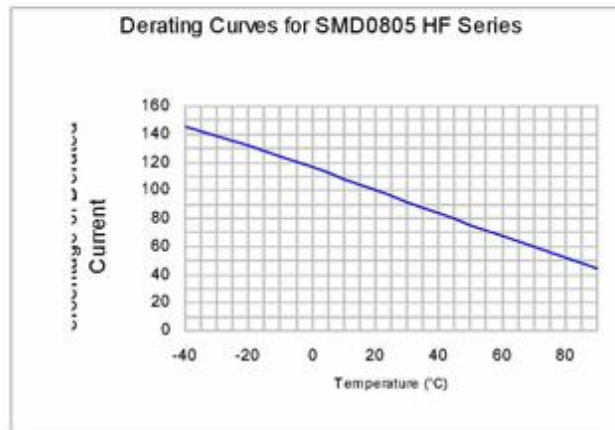
### Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

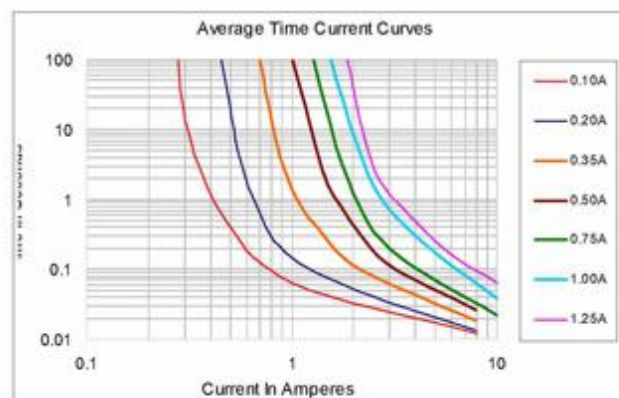
### Termal Derading Chart

Recommended Hold Current (A) at Ambient Temperature (C)									
Model	Ambient Operation Temperature								
	-40C	-20C	0C	25C	40C	50C	60C	70C	85C
0805Z010-15	0.14	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
0805Z020-09	0.28	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
0805Z035-06	0.47	0.44	0.39	0.35	0.30	0.27	0.24	0.20	0.14
0805Z050-06	0.68	0.62	0.55	0.50	0.40	0.37	0.33	0.29	0.23
0805Z075-06	1.00	0.90	0.79	0.75	0.63	0.57	0.53	0.41	0.34
0805Z100-06	1.35	1.25	1.15	1.00	0.82	0.74	0.65	0.55	0.42
0805Z110-06	1.45	1.35	1.20	1.10	0.92	0.84	0.75	0.65	0.52
0805Z125-06	1.65	1.53	1.36	1.25	1.05	0.95	0.85	0.74	0.59

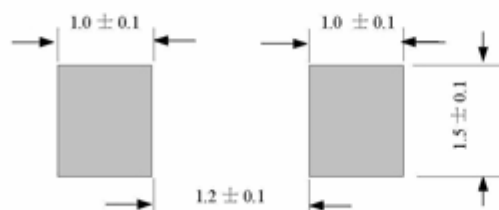
## Thermal Derating Curve



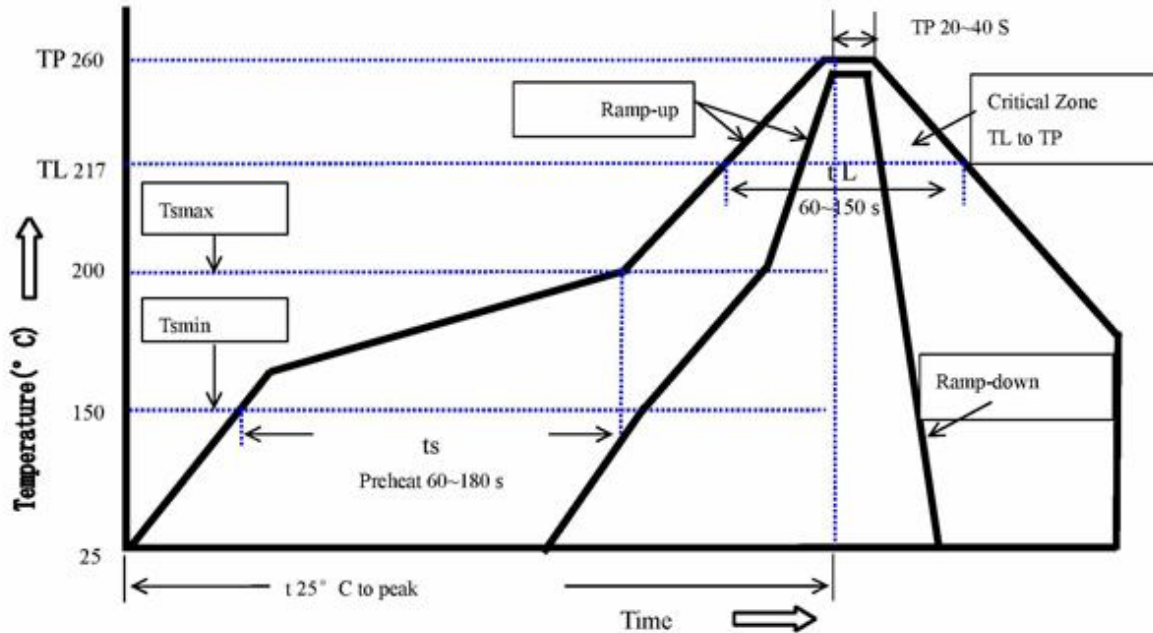
## Average Time-Current Curve



## Recommended Pad Layout (mm.)



## Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate(Ts max to T p)	3°C/second max.
Preheat	
-Temperature Min(Ts min)	150°C
-Temperature Max(Ts max)	200°C
-Time(Ts min to Ts max)	60~180 seconds
Time maintained above:	
-Temperature(TL)	217°C
-Time(tL)	60~150 seconds
Peak Temperature(Tp)	260°C
Ramp-Down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max
Storage Condition	0°C~35°C, ≤70%RH

Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free

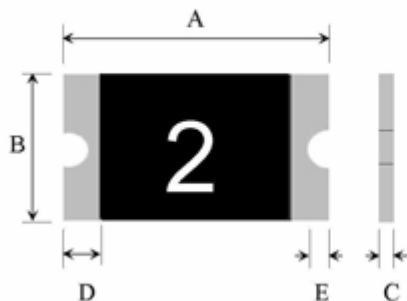
Recommended maximum paste thickness is 0.25mm

Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Physical Dimensions(mm.)



Model	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
0805Z010-15	2.00	2.20	1.20	1.50	0.50	1.00	0.20	0.10
0805Z020-09	2.00	2.20	1.20	1.50	0.45	1.00	0.20	0.10
0805Z035-06	2.00	2.20	1.20	1.50	0.45	1.00	0.20	0.10
0805Z050-06	2.00	2.20	1.20	1.50	0.30	0.60	0.20	0.10
0805Z075-06	2.00	2.20	1.20	1.50	0.40	1.00	0.20	0.10
0805Z100-06	2.00	2.20	1.20	1.50	0.50	1.10	0.20	0.10
0805Z110-06	2.00	2.20	1.20	1.50	0.50	1.20	0.20	0.10
0805Z125-06	2.00	2.20	1.20	1.50	0.50	1.20	0.20	0.10

### Termination Pad Characteristics

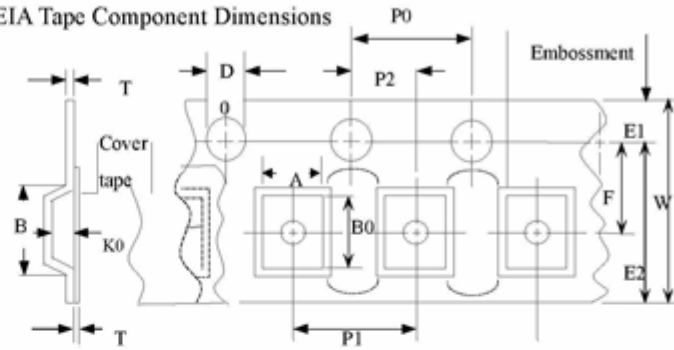
Terminal pad materials: Tin-plated Nickel-Copper

Terminal pad solder ability: Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

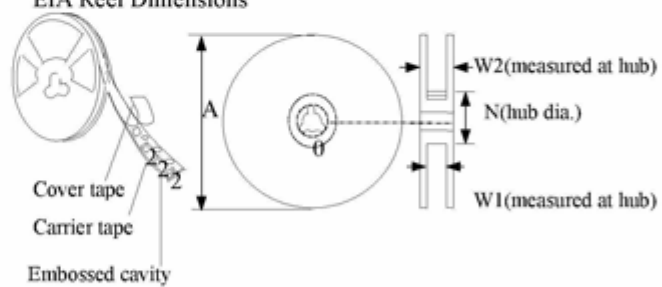
## Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-1
W	$8.0 \pm 0.3$
P0	$4.0 \pm 0.10$
P1	$4.0 \pm 0.10$
P2	$2.0 \pm 0.05$
A0	$1.45 \pm 0.10$
B0	$2.30 \pm 0.10$
B1max.	4.35
D0	$1.55 + 0.1, -0$
F	$3.5 \pm 0.05$
E1	$1.75 \pm 0.10$
E2min.	6.25
T	0.25
T1max.	0.1
K0	$0.74 \pm 0.1$
Leader min.	390
Trailer min.	160
<b>Reel Dimensions</b>	
A max.	178
N min.	60
W1	$9.0 \pm 0.5$
W2	$12.0 \pm 0.05$

EIA Tape Component Dimensions



EIA Reel Dimensions



### Storage And Handling

- Storage conditions: 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.